

Abstract of the Disclosure

An electronic device has a plurality of capacitors in an ultra-small integrated package. The device has a plurality of terminal structures on one terminal side of the package to permit inverted mounting to a printed circuit board. The terminals are widely spaced, with the individual capacitors being located entirely in between. The device is produced on a suitable substrate using thin film manufacturing techniques. A lead-based dielectric having a high dielectric constant is preferably utilized for each capacitor to provide a relatively high-capacitance value in a relatively small plate area.



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